

Japanese Utility-Model Application Laid-Open No. 1-60543

Laid-Open Date: April 17, 1989

1. Title Semiconductor Device

2. Claims of Utility Model

(1) A semiconductor device fabricated by attaching semiconductor members such as semiconductor chips or semiconductor packages to a surface of a flexible insulating sheet, bending the insulating sheet in the shape of the letter "U" with the surface to which the semiconductor members are attached being the inner side, and filling the inner space with an insulating solid material.

(2) The semiconductor device according to claim 1, wherein the solid material is produced by filling the inner space with a resin and allowing the resin to solidify.

(3) The semiconductor device according to claim 1, wherein grounding portions are formed at the ends of opposing portions of the U-shaped insulating sheet at right angles toward the outside, and terminals are formed on the surfaces of the grounding portions.

(4) The semiconductor device according to claim 1, wherein the semiconductor members are provided between inner sides of the opposite portions.